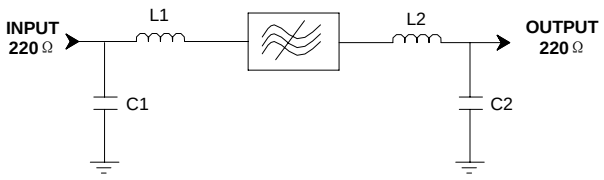
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	211.57	211.65	211.73
Insertion Loss	dB	-	22.8	25
1 dB Bandwidth	MHz	-	5.4	-
1.5 dB Bandwidth	MHz	5.45	5.48	-
3 dB Bandwidth	MHz	-	5.67	-
38 dB Bandwidth	MHz	-	6.61	6.7
40 dB Bandwidth	MHz	-	6.63	-
45 dB Bandwidth	MHz	-	6.71	7.5
Passband Variation	dB	-	0.6	1
Absolute Delay	usec	-	2.36	2.37
Phase Linearity(f0±2.5MHz)	deg	-	4	-
Group Delay Variation(f0±2.5MHz)	nsec	-	80	-
Ultimate Rejection	dB	40	41	-
Material Temperature coefficient	KHz/°C	0.212		
Ambient Temperature	°C	25		
Package Size	DIP2712 (27.0x12.8x4.7mm3)			

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

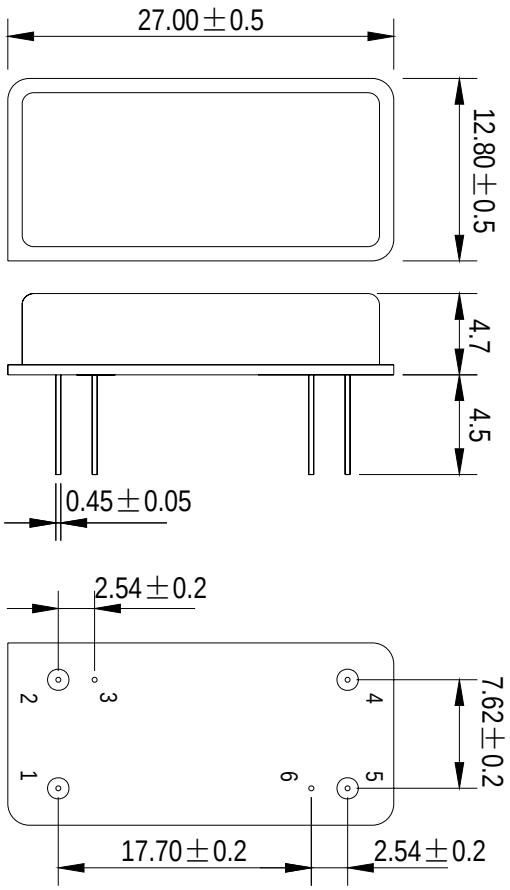
Matching Configuration



L1=L2=47nH
C1=39pF C2=22pF
Source/Load Impedance=220 ohm

Notes - Component values may change depending on board layout.

Package Dimension



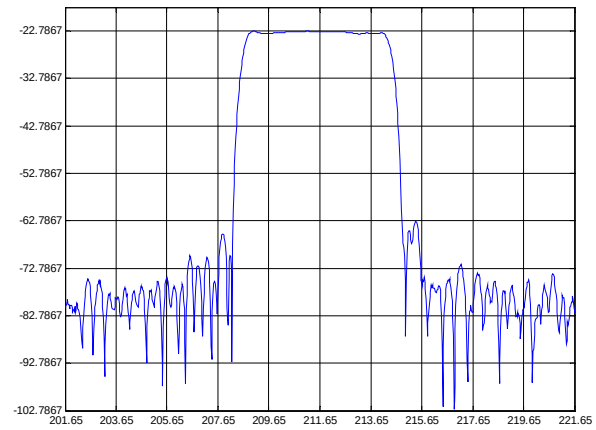
Input	1
Output	5
Ground	2, 3, 4, 6

Package: DIP2712

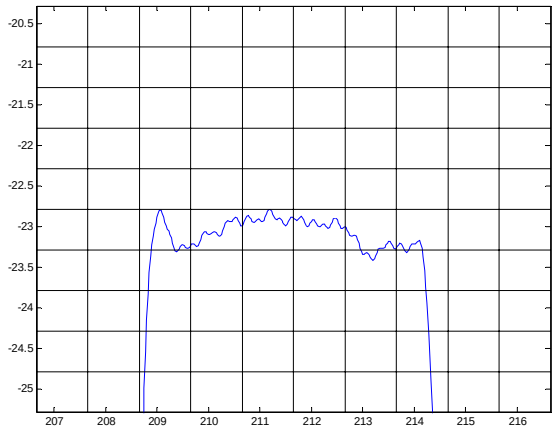
Unit: mm

Typical Performance

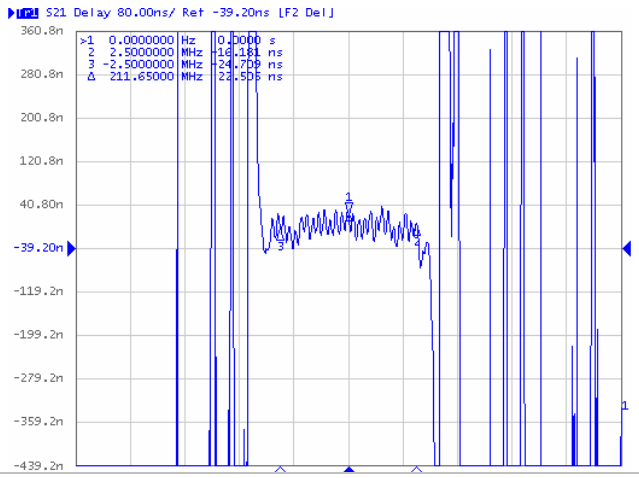
Frequency Respond



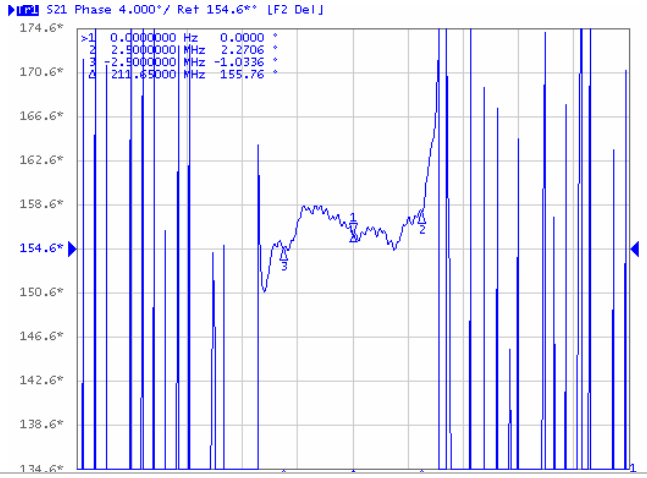
Passband Respond



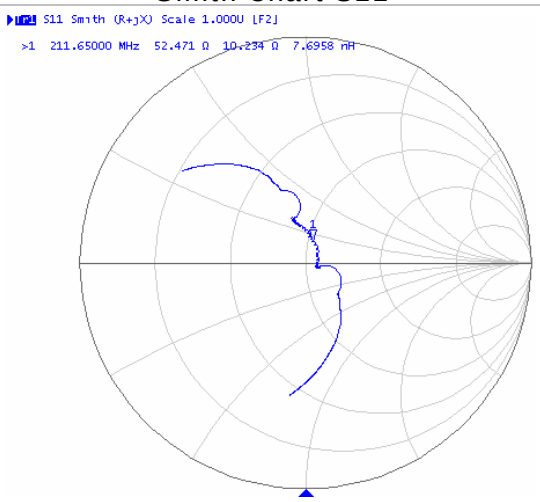
Group Delay Variation(f0±2.5MHz)



Phase Linearity(f0±2.5MHz)



Smith Chart S11



Smith Chart S22

